ZM-R730A BGA Rework Station

Features

- Ceramic honeycomb heating system for Top heater, thermal convert efficiently.
- Carbon fiber heaters for Pre-heating system, wide range for moving around make the PCB Pre-heating more evenly.
- Various operating modes,easily operate, do the chip desoldering and soldering by one key.
- 10 temperature zone control, in line with the lead-free rework process.
- Temperature curve analysis function built-in.
- In order to eliminate the "observation dead angle"problem and ensure the precision for placement, we selected HD optical alignment system which allows all angle observation for BGA edge fast and

convenient.

- X, Y axis with micrometer adjustment, adjustment accuracy up to ± 0.01mm.
- High-precision K-type sensors allows precision detection for different spots in PCB and BGA and analysis temperature curve automatically.
- Standard automatic feeder, feeding and collecting asthmatically.
- Mounting head 360 ° electric rotation.
- Japan THK linear rail for linear motion system which guarantee the running accuracy.
- 10 inch industrial touch screen for HMI
- Panasonic high-performance PLC for motion control, to ensure high stability.
- Japan's Panasonic photoelectric sensor to ensure high reliability.

Main Parameters

Power Supply	AC 380V /AC220 50/60 Hz
Total Power	Max 7500W
Top Heater Power	1200 W
Bottom Heater Power	1200 W
Preheat heater Power	4800 W
IR heater Size	420mm*435mm
Mount precision:	±0.01mm
PCB Thickness	0.5~8mm
Mount Pressure	< 0.2N
Hot Air Heating Temperature	400℃（Max）
PCB Max Size	645mm×520mm
Chip Size Range	3×3mm--80×80mm
Worktable Fine Tuner	X & Y 1CM
Measurement	L1000×W840×H950mm
Sensor	5pcs
Machine Weight	128kg
Color	White&Grey